HMB-6110

Compute Blade for HTCA-6000 Series Based on 2nd Generation Intel® Xeon® Scalable Processors (codenamed Purley)



Features

- Hot swappable x86 compute blade
- Support dual 2nd Generation Intel® Xeon® Scalable Processors (codenamed Purley) and C621/C627 PCH
- 16x 288-pin DDR4 DIMMs, max. up to 512GB memory capacity
- 4x KR4 support 4x 100G to front Switch blades

Product I/O View

• 5x Hot swappable smart fans

Preliminary Specifications

System	
CPU	Dual Intel 2nd Generation Intel® Xeon® Scalable
	Processors (codenamed Skylake-SP/Cascade Lake-SP)
	with C621/C627 PCH
Memory	16x 288-pin DDR4 DIMMs, max. up to 512GB
	memory capacity
Interface	
	 LAN: Intel Ethernet 800 Series 100G(KR4) x 2 to top 1st layer switch blade 100G(KR4) x2 to top 2nd layer switch blade Intel I210 1GbE x2 5x PCI-Express Gen3 by 8 (To front side mod- ule) 1x PCI-Express Gen 2 (To front side module) 1x OPMA connector 1x M.2 2280 M Key Socket (SATA3/PCIe x4) 1x pin header for TPM 2.0 module (Optional)
Rear IO	
	 1x miniDP (VGA signal) 1x RJ45 management port on rear side 1x USB 2.0
System Compatibility	
	HTCA-6200, HTCA-6400 and HTCA-6600
Temperature	
Operating	0 ~ 40°C
Storage	-40~70°C
Humidity	
	5%~90%. non-condensing
Mechanical	
Dimension (W x H x D)	327.4 x 41 x 466 mm
Weight	8 kg
Certification	
CE	Class A
FCC	Class A

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High speed connector
OPMA slot
Cooling fans
USB 2.0, RJ45 management port and mini-DP

Ordering Information

	Skylake-SP/Cascade Lake-SP x2 sockets,
HMB-6110A	DDR4 sockets x16 with tray, C627 (with
	QAT) Skylake-SP/Cascade Lake-SP x2 sockets,
HMB-6110B	DDR4 sockets x16 with tray, C621
	(without QAT)

V2-2021,12,9

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